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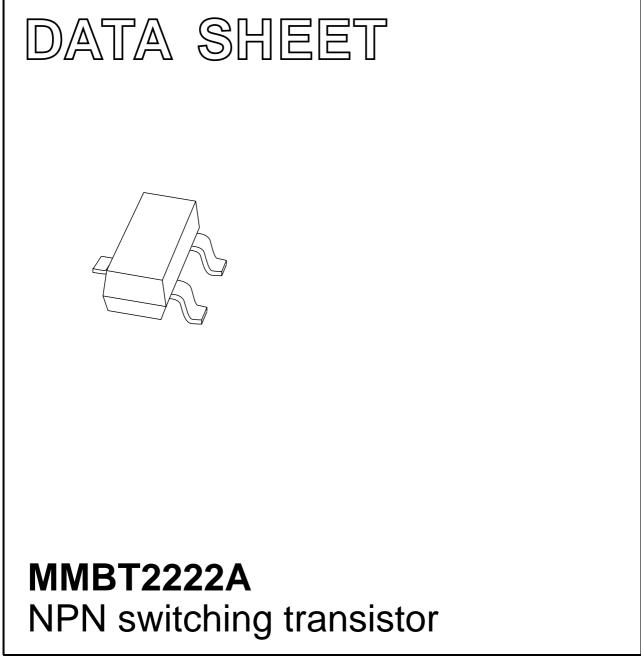
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Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2000 Apr 11 2004 Jan 16



MMBT2222A

NPN switching transistor

FEATURES

- High current (max. 600 mA)
- Low voltage (max. 40 V).

APPLICATIONS

• Switching and linear amplification.

DESCRIPTION

NPN switching transistor in a SOT23 plastic package. PNP complement: PMBT2907A.

MARKING

TYPE NUMBER	MARKING CODE ⁽¹⁾	
MMBT2222A	7C*	

Note

- 1. * = p: Made in Hong Kong.
 - * = t : Made in Malaysia.

* = W : Made in China.

ORDERING INFORMATION

TYPE		PACKAGE		
NUMBER	NAME	NAME DESCRIPTION VE		
MMBT2222A	_	 plastic surface mounted package; 3 leads 		

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	75	V
V _{CEO}	collector-emitter voltage	open base	-	40	V
V _{EBO}	emitter-base voltage	open collector	-	6	V
I _C	collector current (DC)		-	600	mA
I _{CM}	peak collector current		-	800	mA
I _{BM}	peak base current		-	200	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$; note 1	-	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

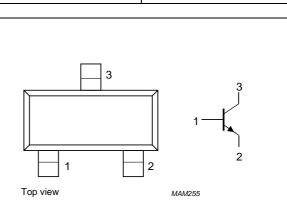


Fig.1 Simplified outline (SOT23) and symbol.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector

MMBT2222A

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

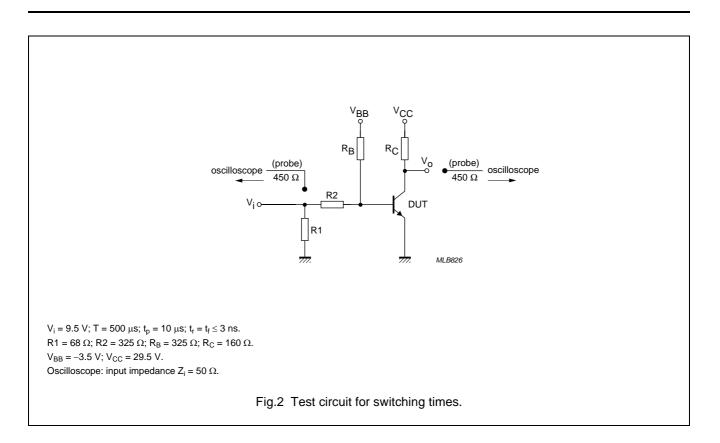
 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO} C	collector cut-off current	I _E = 0; V _{CB} = 60 V	_	10	nA
		I _E = 0; V _{CB} = 60 V; T _j = 125 °C	_	10	μA
I _{EBO}	emitter cut-off current	I _C = 0; V _{EB} = 5 V	_	10	nA
h _{FE}	DC current gain	I _C = 0.1 mA; V _{CE} = 10 V	35	_	
		I _C = 1 mA; V _{CE} = 10 V	50	_	
		I _C = 10 mA; V _{CE} = 10 V	75	_	
		$I_C = 10 \text{ mA}; V_{CE} = 10 \text{ V};$ $T_{amb} = -55 ^{\circ}\text{C}$	35	-	
		I _C = 150 mA; V _{CE} = 10 V	100	300	
		I _C = 150 mA; V _{CE} = 1 V	50	_	
		I _C = 500 mA; V _{CE} = 10 V	40	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = 150 mA; I _B = 15 mA; note 1	_	300	mV
		$I_{C} = 500 \text{ mA}; I_{B} = 50 \text{ mA}; \text{ note } 1$	_	1	V
V _{BEsat}	base-emitter saturation voltage	I _C = 150 mA; I _B = 15 mA; note 1	0.6	1.2	V
		$I_{C} = 500 \text{ mA}; I_{B} = 50 \text{ mA}; \text{ note } 1$	_	2	V
C _c	collector capacitance	$I_E = i_e = 0; V_{CB} = 10 V;$ f = 1 MHz	-	8	pF
C _e	emitter capacitance	$I_{C} = i_{c} = 0; V_{EB} = 500 \text{ mV};$ f = 1 MHz	-	25	pF
f _T	transition frequency	$I_{C} = 20 \text{ mA}; V_{CE} = 20 \text{ V};$ f = 100 MHz	300	-	MHz
F	noise figure $I_{C} = 100 \ \mu\text{A}; \ V_{CE} = 5 \ \text{V}; \\ R_{S} = 1 \ \text{k}\Omega; \ \text{f} = 1 \ \text{kHz}$		-	4	dB
Switching t	imes (between 10% and 90% levels); (se	ee Fig.2)			
t _{on}	turn-on time	I _{Con} = 150 mA; I _{Bon} = 15 mA;	-	35	ns
t _d	delay time	$I_{Boff} = -15 \text{ mA}$	_	15	ns
t _r	rise time		_	20	ns
t _{off}	turn-off time		-	250	ns
ts	storage time		_	200	ns
t _f	fall time		-	60	ns

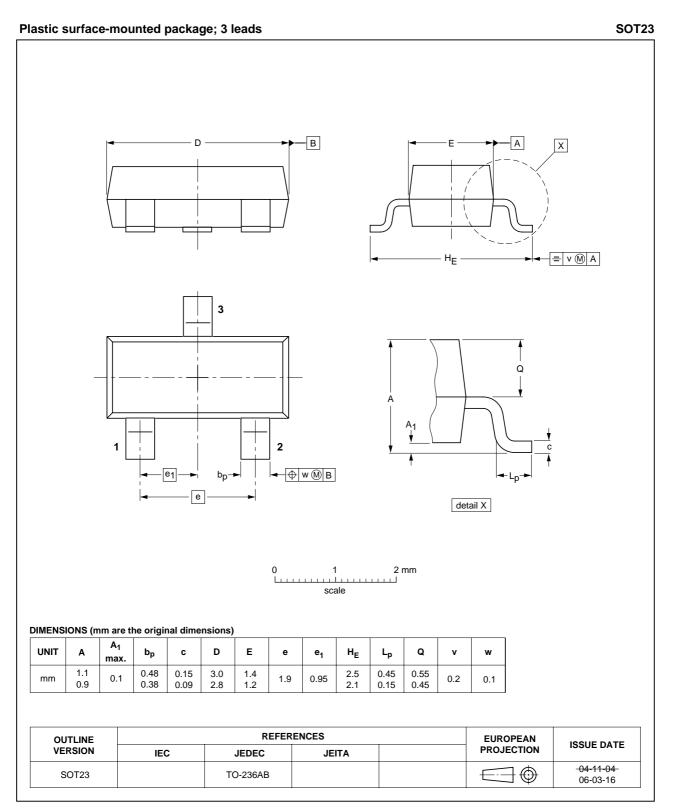
Note

1. Pulse test: $t_p \leq 300~\mu s;~\delta \leq 0.02.$

MMBT2222A



PACKAGE OUTLINE



MMBT2222A

MMBT2222A

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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NXP Semiconductors

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Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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